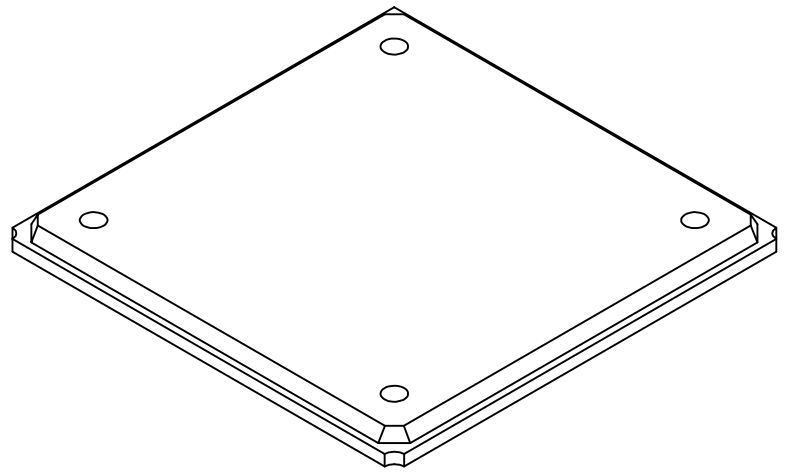
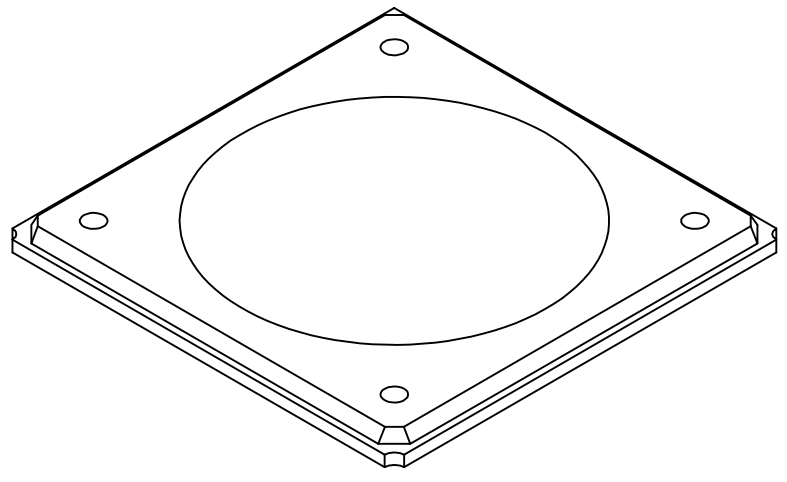
REVISION HISTORY

REV	DCN NUMBER	DESCRIPTION	ORIGINATOR	DATABASE FILE NAME	GERBER FILE NAME	INCORPORATOR	DATE
01	C12344	CORRECTED BALL LETTERING SEQUENCE	DARNO	N/A	N/A	DARNO	04/23/01
02	C14443	ADDED TEPBGA–2 PACKAGE	DARNO	N/A	N/A	DARNO	12/03/01
03	C15761	ADD 1005 MATRIX, MARK AREA WAS 31.0	DARNO	N/A	N/A	DARNO	05/01/02
04	C16098	CAP TOLERANCE WAS 38.70 +0.70/–0.05 ADD 1061 MATRIX,	DARNO	N/A	N/A	DARNO	05/14/02
05	C21251	ADD 1069 MATRIX, TEPBGA/TEPBGA–2 SUBSTRATE THICKNESS WAS 0.61	TGROE	N/A	N/A	TGROE	01/13/03



PBGA
TEPBGA



TEPBGA–2

7. REFERENCE SPECIFICATIONS:
   A. AWW SPEC #001–0531–2234: PACKING OPERATION PROCEDURE.
   B. AWW SPEC #001–0519–2062: MARKING.
   C. THIS DRAWING CONFORMS TO THE JEDEC REGISTERED OUTLINE MS–034/A VARIATION AAU–1.

6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 1521.

3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 39 X 39.

2. THE BASIC SOLDER BALL GRID PITCH IS 1.00mm.

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M–1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS
DECIMAL X.X ±0.1, X.XX ±0.05, X.XXX ±0.030
ANGULAR ±1°
INTERPRET DIM AND TOL PER ASME Y14.5M – 1994
MATERIAL: SEE CROSS SECTION
FINISH: SEE NOTE 1
DO NOT SCALE DRAWING

THIRD ANGLE PROJECTION

APPROVALS	DATE
DESIGNED CCOAD	12/05/00
CHECKED JMICK	12/05/00
PRODUCT MANAGER BGOGU	12/05/00
RELEASED RHOLM	01/29/01

Amkor Technology, Inc.
Chandler, Arizona, USA
Anam Semiconductor, Inc.,
Seoul, Korea
Amkor Technology Philippines, Inc.
Manila, Philippines

Amkor Technology / ANAM Semiconductor

TITLE: PACKAGE OUTLINE – PBGA CUSTOM, 39 X 39 MATRIX, 40.00mm X 40.00mm, 38.70mm X 38.70mm X 1.17mm MOLD CAP, 1.00mm PITCH, LAMINATE SUBSTRATE, AWW

SIZE	SID NUMBER	DWG NUMBER	REV
A3	N/A	81949	05

STRIP DWG NUMBER/REV	PKG OUTLINE DWG NO.	SCALE	SHEET
N/A	N/A	NONE	1 OF 6